



Product/Process Change Notice - PCN 23_0268 Rev. -

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This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Bond Wire Conversion and Mold Compound Change for ADSP-BF70x/BF70xW Processors in 184-Ball BGA Package
Publication Date:	23-Jan-2024
Effectivity Date:	26-Apr-2024 <i>(the earliest date that a customer could expect to receive changed material)</i>
Revision Description:	Initial Release.

Description Of Change:

Change of bond wire material from Gold (Au) to Copper (Cu) and change of molding compound from Sumitomo G770LC to Kyocera KE G1280TS.

Reason For Change:

Ensure continuity of supply in order to meet customer demand.

Impact of the change (positive or negative) on fit, form, function & reliability:

There is no change to form, fit, functionality or reliability.

Product Identification *(this section will describe how to identify the changed material)*

Change will be differentiated by date code.

Summary of Supporting Information:

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

[ADI_PCN_23_0268_Rev_-_Qualification_Report.pdf...](#)

Attachment 2: Type: Delta Qualification Matrix

[ADI_PCN_23_0268_Rev_-_Delta-Qualification-Matrix-ZVEI-5_0_16.xlsm...](#)

Attachment 3: Type: Detailed Change Description

[ADI_PCN_23_0268_Rev_-_184-ball_BGA_Material_Changes.pdf...](#)

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Rest of Asia:
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Appendix A - Affected ADI Models:

Added Parts On This Revision - Product Family / Model Number (26)

ADSP-BF701 / ADSP-BF701BBCZ-2	ADSP-BF701 / ADSP-BF701KBCZ-1	ADSP-BF701 / ADSP-BF701KBCZ-2	ADSP-BF701W-11 / ADBF701WCBCZ211	ADSP-BF703 / ADSP-BF703BBCZ-3
ADSP-BF703 / ADSP-BF703BBCZ-4	ADSP-BF703 / ADSP-BF703KBCZ-3	ADSP-BF703 / ADSP-BF703KBCZ-4	ADSP-BF703W-11 / ADBF703WCBCZ311	ADSP-BF703W-11 / ADBF703WCBCZ411
ADSP-BF705 / ADSP-BF705BBCZ-3	ADSP-BF705 / ADSP-BF705BBCZ-4	ADSP-BF705 / ADSP-BF705KBCZ-3	ADSP-BF705 / ADSP-BF705KBCZ-4	ADSP-BF705W-11 / ADBF705WCBCZ311
ADSP-BF705W-11 / ADBF705WCBCZ411	ADSP-BF707 / ADSP-BF707BBCZ-3	ADSP-BF707 / ADSP-BF707BBCZ-4	ADSP-BF707 / ADSP-BF707BBCZ-4RL	ADSP-BF707 / ADSP-BF707KBCZ-3
ADSP-BF707 / ADSP-BF707KBCZ-4	ADSP-BF707 / ADSPBF707BBCZ4- EGE	ADSP-BF707W-11 / ADBF707WCBCZ311	ADSP-BF707W-11 / ADBF707WCBCZ411	ADSW4000 / ADSW4000-P
ADSW4000 / ADSW4000-Y				

Appendix B - Revision History:			
Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	23-Jan-2024	26-Apr-2024	Initial Release.